14 JUN 2002



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METHOD FOR MOUNTING SEMICONDUCTOR CHIPS

ABSTRACT

When mounting semiconductor chips (3), the semiconductor chips are presented on a carrier foil (2). Unusable semiconductor chips are not marked with ink but data concerning the usability of the semiconductor chips and eventual further data concerning their quality are stored in a database known as a wafermap. When, on the carrier foil, the distance between the next semiconductor chip to be mounted (3b) and the last semiconductor chip mounted (3b) exceeds a predetermined value, the automatic assembly equipment approaches at least one intermediate position and determines its actual position based on the position of the sawing tracks (4) left in the carrier foil during sawing. If the determined actual position deviates from the set position, the difference is taken into consideration on approaching the next intermediate position or the next semiconductor chip.

(Fig 1)

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